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Kind regards,

Team Nexperia

74HC1G126; 74HCT1G126

Bus buffer/line driver; 3-state

Rev. 04 — 20 July 2007 Product data sheet

1. General description

The 74HC1G126 and 74HCT1G126 are high-speed, Si-gate CMOS devices. They provide one non-inverting buffer/line driver with 3-state output. The 3-state output is controlled by the output enable input pin (OE). A LOW at pin OE causes the output as assume a high-impedance OFF-state.

The HC device has CMOS input switching levels and supply voltage range 2 V to 6 V.

The HCT device has TTL input switching levels and supply voltage range 4.5 V to 5.5 V.

The bus driver output currents are equal to those of the 74HC126 and 74HCT126.

2. Features

- Symmetrical output impedance
- High noise immunity
- Low power dissipation
- Balanced propagation delays
- SOT353-1 and SOT753 package options

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC1G126GW	–40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74HCT1G126GW				
74HC1G126GV	–40 °C to +125 °C	SC-74A	plastic surface-mounted package; 5 leads	SOT753
74HCT1G126GV				

4. Marking

Table 2. Marking codes

Type number	Marking
74HC1G126GW	HN
74HCT1G126GW	TN
74HC1G126GV	H26
74HCT1G126GV	T26

5. Functional diagram

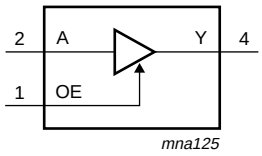


Fig 1. Logic symbol

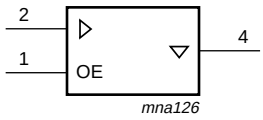


Fig 2. IEC logic symbol

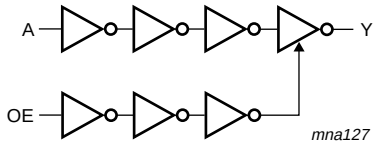


Fig 3. Logic diagram

6. Pinning information

6.1 Pinning

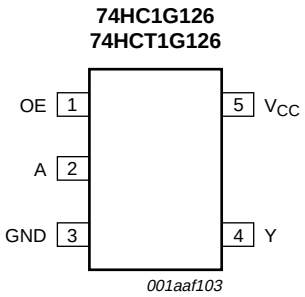


Fig 4. Pin configuration

6.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
OE	1	output enable input
A	2	data input
GND	3	ground (0 V)
Y	4	data output
V_{CC}	5	supply voltage

7. Functional description

Table 4. Function table

H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state

Inputs		Output
OE	**A**	**Y**
H	L	L
H	H	H
L	X	Z

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V). [1]

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage			–0.5	+7.0	V
I_{IK}	input clamping current	$V_I < –0.5$ V or $V_I > V_{CC} + 0.5$ V		-	±20	mA
I_{OK}	output clamping current	$V_O < –0.5$ V or $V_O > V_{CC} + 0.5$ V		-	±20	mA
I_O	output current	$–0.5$ V $< V_O < V_{CC} + 0.5$ V		-	±35.0	mA
I_{CC}	supply current			-	70	mA
I_{GND}	ground current			–70	-	mA
T_{stg}	storage temperature			–65	+150	°C
P_{tot}	total power dissipation	T_{amb} = –40 °C to +125 °C	[2]	-	200	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] Above 55 °C the value of P_{tot} derates linearly with 2.5 mW/K.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	74HC1G126			74HCT1G126			Unit
			Min	Typ	Max	Min	Typ	Max	
V_{CC}	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V_I	input voltage		0	-	V_{CC}	0	-	V_{CC}	V
V_O	output voltage		0	-	V_{CC}	0	-	V_{CC}	V
T_{amb}	ambient temperature		–40	+25	+125	–40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	V_{CC} = 2.0 V	-	-	625	-	-	-	ns/V
		V_{CC} = 4.5 V	-	-	139	-	-	139	ns/V
		V_{CC} = 6.0 V	-	-	83	-	-	-	ns/V

10. Static characteristics

Table 7. Static characteristics

Voltages are referenced to GND (ground = 0 V). All typical values are measured at T_{amb} = 25 °C.

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	
For type 74HC1G126								
V_{IH}	HIGH-level input voltage	V_{CC} = 2.0 V	1.5	1.2	-	1.5	-	V
		V_{CC} = 4.5 V	3.15	2.4	-	3.15	-	V
		V_{CC} = 6.0 V	4.2	3.2	-	4.2	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 2.0 V	-	0.8	0.5	-	0.5	V
		V_{CC} = 4.5 V	-	2.1	1.35	-	1.35	V
		V_{CC} = 6.0 V	-	2.8	1.8	-	1.8	V

Table 7. Static characteristics *...continued*

Voltages are referenced to GND (ground = 0 V). All typical values are measured at T_{amb} = 25 °C.

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}						
		I_O = –20 µA; V_{CC} = 2.0 V	1.9	2.0	-	1.9	-	V
		I_O = –20 µA; V_{CC} = 4.5 V	4.4	4.5	-	4.4	-	V
		I_O = –20 µA; V_{CC} = 6.0 V	5.9	6.0	-	5.9	-	V
		I_O = –6.0 mA; V_{CC} = 4.5 V	3.84	4.32	-	3.7	-	V
		I_O = –7.8 mA; V_{CC} = 6.0 V	5.34	5.81	-	5.2	-	V
V_{OL}	LOW-level output voltage	V_I = V_{IH} or V_{IL}						
		I_O = 20 µA; V_{CC} = 2.0 V	-	0	0.1	-	0.1	V
		I_O = 20 µA; V_{CC} = 4.5 V	-	0	0.1	-	0.1	V
		I_O = 20 µA; V_{CC} = 6.0 V	-	0	0.1	-	0.1	V
		I_O = 6.0 mA; V_{CC} = 4.5 V	-	0.15	0.33	-	0.4	V
		I_O = 7.8 mA; V_{CC} = 6.0 V	-	0.16	0.33	-	0.4	V
I_I	input leakage current	V_I = V_{CC} or GND; V_{CC} = 6.0 V	-	-	1.0	-	1.0	µA
I_{OZ}	OFF-state output current	V_I = V_{IH} or V_{IL}; V_O = V_{CC} or GND; V_{CC} = 6.0 V	-	-	5	-	10	µA
I_{CC}	supply current	V_I = V_{CC} or GND; I_O = 0 A; V_{CC} = 6.0 V	-	-	10	-	20	µA
C_I	input capacitance		-	1.5	-	-	-	pF
For type 74HCT1G126								
V_{IH}	HIGH-level input voltage	V_{CC} = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	V
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}; V_{CC} = 4.5 V						
		I_O = –20 µA	4.4	4.5	-	4.4	-	V
		I_O = –6.0 mA	3.84	4.32	-	3.7	-	V
V_{OL}	LOW-level output voltage	V_I = V_{IH} or V_{IL}; V_{CC} = 4.5 V						
		I_O = 20 µA	-	0	0.1	-	0.1	V
		I_O = 6.0 mA	-	0.16	0.33	-	0.4	V
I_I	input leakage current	V_I = V_{CC} or GND; V_{CC} = 5.5 V	-	-	1.0	-	1.0	µA
I_{OZ}	OFF-state output current	V_I = V_{IH} or V_{IL}; V_O = V_{CC} or GND; V_{CC} = 5.5 V	-	-	5	-	10	
I_{CC}	supply current	V_I = V_{CC} or GND; I_O = 0 A; V_{CC} = 5.5 V	-	-	10	-	20	µA
ΔI_{CC}	additional supply current	per input; V_{CC} = 4.5 V to 5.5 V; V_I = V_{CC} – 2.1 V; I_O = 0 A	-	-	500	-	850	µA
C_I	input capacitance		-	1.5	-	-	-	pF

11. Dynamic characteristics

Table 8. Dynamic characteristics

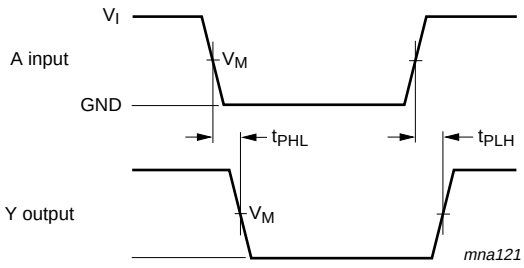
GND = 0 V; $t_r = t_f \leq 6.0$ ns; C_L = 50 pF unless otherwise specified. All typical values are measured at T_{amb} = 25 °C. For test circuit see Figure 7

Symbol	Parameter	Conditions		−40 °C to +85 °C			−40 °C to +125 °C		Unit
				Min	Typ	Max	Min	Max	
For type 74HC1G126									
t_{pd}	propagation delay	A to Y; see Figure 5	[1]						
		V_{CC} = 2.0 V		-	24	125	-	150	ns
		V_{CC} = 4.5 V		-	10	25	-	30	ns
		V_{CC} = 5.0 V; C_L = 15 pF		-	9	-	-	-	ns
		V_{CC} = 6.0 V		-	9	21	-	26	ns
t_{en}	enable time	OE to Y; see Figure 6	[1]						
		V_{CC} = 2.0 V		-	24	155	-	190	ns
		V_{CC} = 4.5 V		-	10	31	-	38	ns
		V_{CC} = 6.0 V		-	8	26	-	32	ns
t_{dis}	disable time	OE to Y; see Figure 6	[1]						
		V_{CC} = 2.0 V		-	16	155	-	190	ns
		V_{CC} = 4.5 V		-	12	31	-	38	ns
		V_{CC} = 6.0 V		-	11	26	-	32	ns
C_{PD}	power dissipation capacitance	V_I = GND to V_{CC}	[2]	-	30	-	-	-	pF
For type 74HCT1G126									
t_{pd}	propagation delay	A to Y; see Figure 5	[1]						
		V_{CC} = 4.5 V		-	11	30	-	36	ns
		V_{CC} = 5.0 V; C_L = 15 pF		-	10	-	-	-	ns
t_{en}	enable time	OE to Y; see Figure 6; V_{CC} = 4.5 V	[1]	-	10	35	-	42	ns
t_{dis}	disable time	OE to Y; see Figure 6; V_{CC} = 4.5 V	[1]	-	12	31	-	38	ns
C_{PD}	power dissipation capacitance	V_I = GND to V_{CC} − 1.5 V	[2]	-	27	-	-	-	pF

[1] t_{pd} is the same as t_{PLH} and t_{PHL}.
t_{en} is the same as t_{PZL} and t_{PZH}.
t_{dis} is the same as t_{PLZ} and t_{PHZ}.

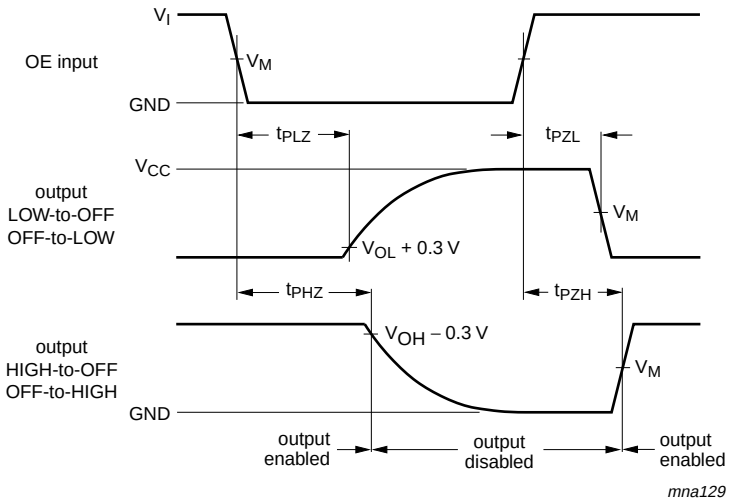
[2] C_{PD} is used to determine the dynamic power dissipation P_D (µW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:
f_i = input frequency in MHz
f_o = output frequency in MHz
C_L = output load capacitance in pF
V_{CC} = supply voltage in Volts
$\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs

12. Waveforms



Measurement points are given in Table 9.

Fig 5. The input (A) to output (Y) propagation delays

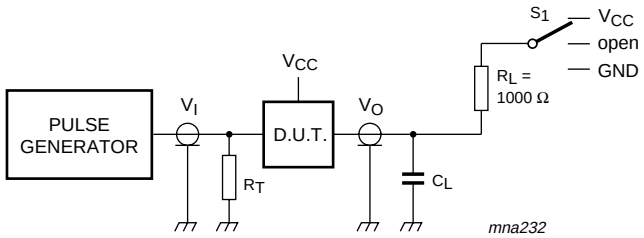


Measurement points are given in Table 9.

Fig 6. The 3-state enable and disable times

Table 9. Measurement points

Type	Input		Output
	V_M	V_I	V_M
74HC1G126	$0.5 \times V_{CC}$	GND to V_{CC}	$0.5 \times V_{CC}$
74HCT1G126	1.3 V	GND to 3.0 V	1.3 V



Test data is given in Table 8. Definitions for test circuit:

R_T = Termination resistance should be equal to the output impedance Z_o of the pulse generator

C_L = Load capacitance including jig and probe capacitance

R_L = Load resistance

For t_{PLH}, t_{PHL}, S_1 = open

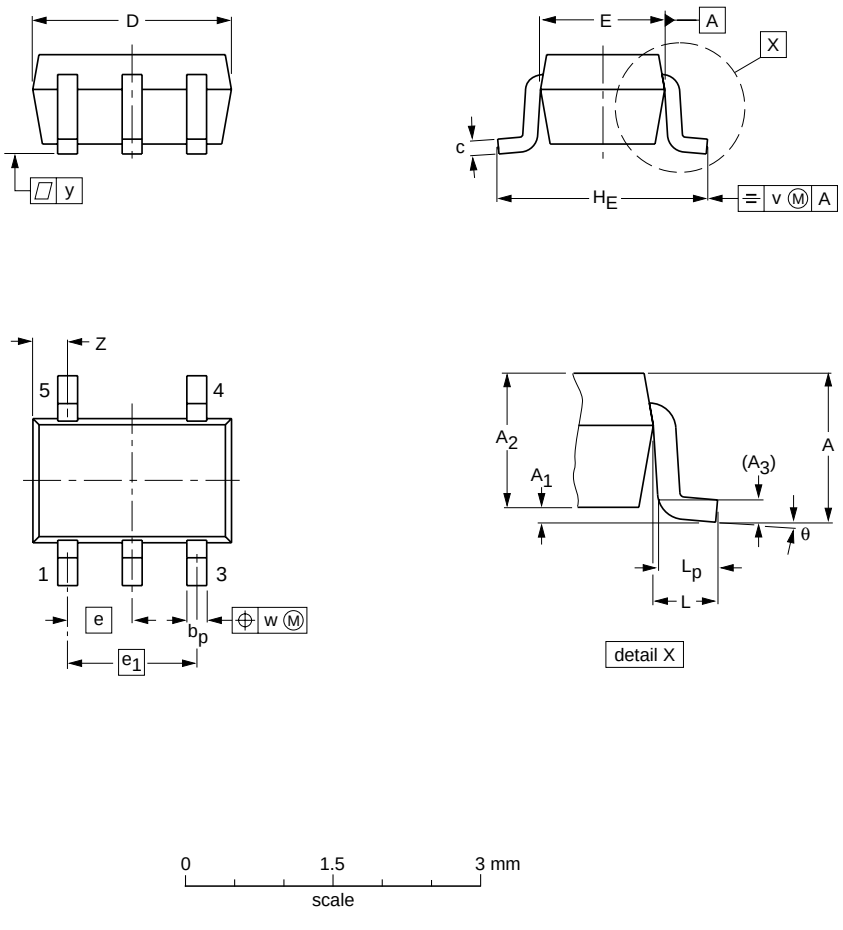
For t_{PLZ}, t_{PZL}, S_1 = V_{CC}

For t_{PHZ}, t_{PZH}, S_1 = GND

Fig 7. Load circuitry for switching times

13. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm **SOT353-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	e_1	H_E	L	L_p	v	w	y	$Z^{(1)}$	θ
mm	1.1	0.1 0	1.0 0.8	0.15	0.30 0.15	0.25 0.08	2.25 1.85	1.35 1.15	0.65	1.3	2.25 2.0	0.425	0.46 0.21	0.3	0.1	0.1	0.60 0.15	7° 0°

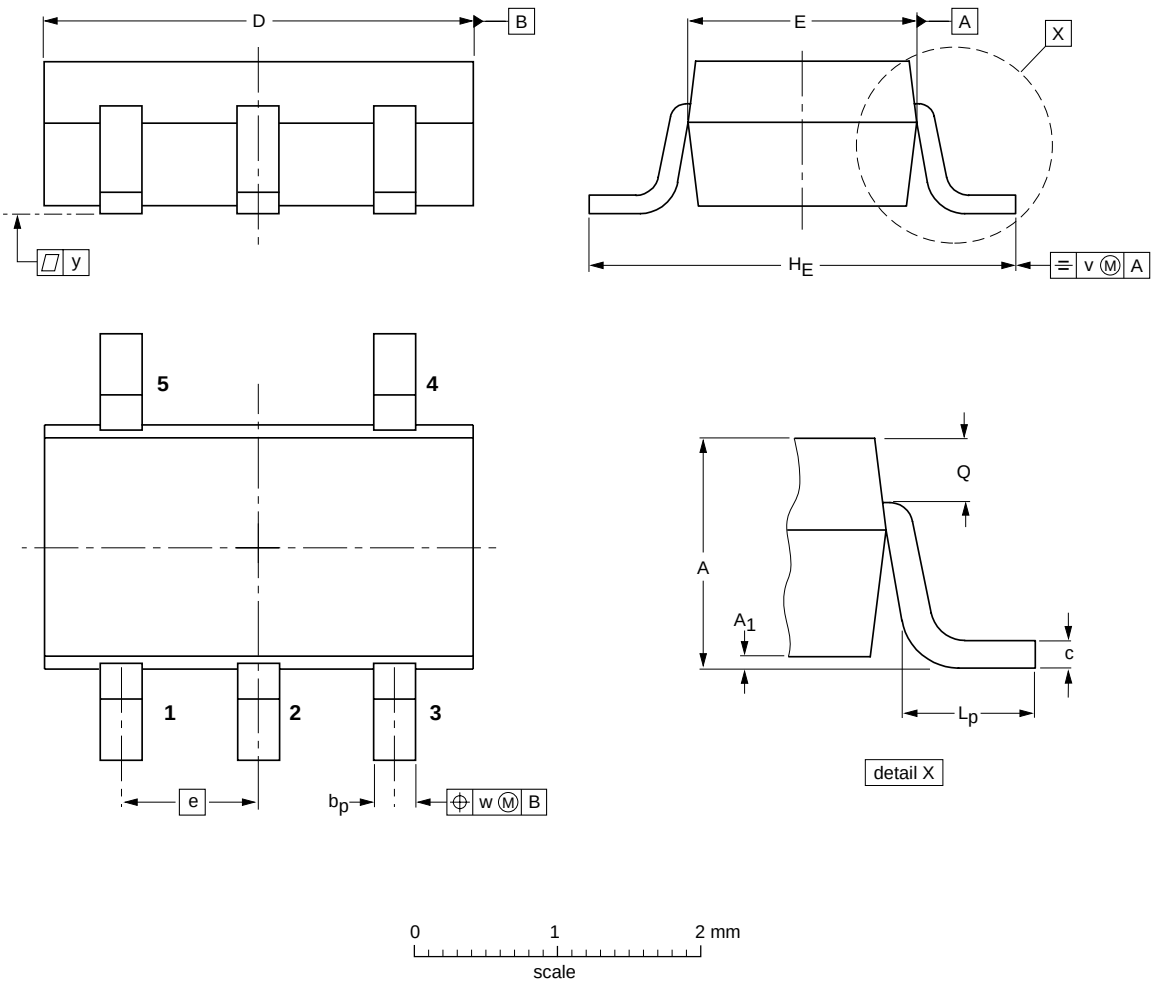
Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT353-1		MO-203	SC-88A			~~00-09-01~~ 03-02-19

Fig 8. Package outline SOT353-1 (TSSOP5)

Plastic surface-mounted package; 5 leads **SOT753**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	b_p	c	D	E	e	H_E	L_p	Q	v	w	y
mm	1.1 0.9	0.100 0.013	0.40 0.25	0.26 0.10	3.1 2.7	1.7 1.3	0.95	3.0 2.5	0.6 0.2	0.33 0.23	0.2	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT753			SC-74A			~~02-04-16~~ 06-03-16

Fig 9. Package outline SOT753 (SC-74A)

14. Abbreviations

Table 10. Abbreviations

Acronym	Description
DUT	Device Under Test
TTL	Transistor-Transistor Logic

15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT1G126_4	20070720	Product data sheet	-	74HC_HCT1G126_3
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Package SOT353 changed to SOT353-1 in Table 1 and Figure 8. • Quick Reference Data and Soldering sections removed. • Section 2 “Features” updated.			
74HC_HCT1G126_3	20020515	Product specification	-	74HC_HCT1G126_2
74HC_HCT1G126_2	20010406	Product specification	-	74HC_HCT1G126
74HC_HCT1G126	19970924	Preliminary specification	-	-

16. Legal information

16.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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18. Contents

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Date of release: 20 July 2007
Document identifier: 74HC_HCT1G126_4